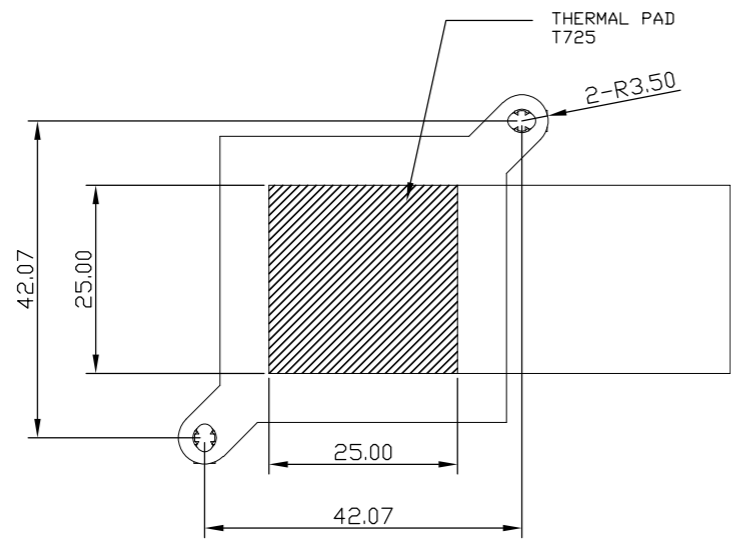


DETAIL A
SCALE 5:1



- NOTES:
1. INTERPRET DRAWING PER ASME Y14.5M-1994.
 2. MATERIAL:
HEATSINK;ALUMINUM 6063 T5 SURFACE TREATMENT WITH BLACK
THERMAL PAD: T725
PUSH PIN: CUSTOMER DESIGNATED PARTS, SUPPLIER IS FREROX ELECTRONICS, SUPPLIER P/N IS MCC-1, COLOR IS BLACK.
 3. ALL EDGES AND CORNERS MUST MEET SAFE HANDLING.
 4. RoHS COMPLIANT AND CERTIFIED.
 5. USE FOR CHASSIS HOLE WITH DIA. 3 TO 3.2 MM.
 6. USE FOR THICKNESS OF CHASSIS AND CHIP WITH 3.8 TO 4.8 MM.

THIS INFORMATION IS CONFIDENTIAL AND PROPRIETARY TO TYCO ELECTRONICS CORPORATION AND ITS WORLDWIDE SUBSIDIARIES AND AFFILIATES. IT MAY NOT BE DISCLOSED TO ANYONE, OTHER THAN TYCO ELECTRONICS PERSONNEL, WITHOUT WRITTEN AUTHORIZATION FROM TYCO ELECTRONICS CORPORATION, HARRISBURG, PENNSYLVANIA USA.

LOC	-
DIST	-

	A	INITIAL RELEASE	5MAY2008	ERIC	MICD
P	LTR	REVISION RECORD	DATE	DWN	APVD

TYCO PART NO: 5-1961000-0		DWN Eric Han 29JUN2007	MATERIAL See Notes	HEAT TREAT N/A
DIMENSIONS: mm		CHK Mico Yu 29JUN2007	Tyco Electronics Corporation Zhuhai Guangdong	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1.00 1 PLC ± 0.50 2 PLC ± 0.30 3 PLC ± 0.13 4 PLC ± 0.06		APVD Mico Yu 29JUN2007		
ANGLES ± 2° SURFACE TEXTURE		NAME CHIPSET HEATSINK FOR PHILIPS		
SCALE 1:1	SIZE A3	DRAWING NO C-5-1961000-0	SHEET 1 OF 1	REV A